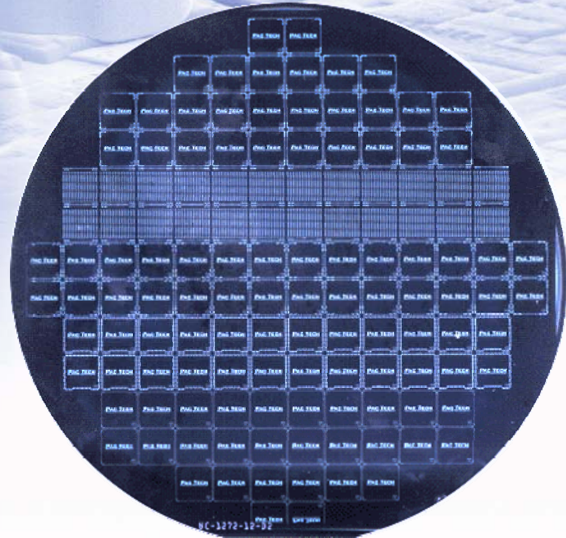
PAC TECH
PACKAGING TECHNOLOGIES

SERVICE
EQUIPMENT
PROCESSES

Flip Chip Test Kit Pac 2.0
For FCOB / FCIP



Wafer Specifications

•6" Silicon Wafer

•General Data:

105 chips	**10x10mm**
21x chip 1:	200µm pitch peripheral 184 I/O's
21x chip 2:	300µm pitch peripheral 120 I/O's
21x chip 3:	200/400 µm pitch area 572 I/O's
21x chip 4:	250µm pitch staggered 248 I/O's
21x chip 5:	200µm pitch peripheral 376 I/O's

•Bump Specifications:
Available with following bump types:

Electroless Ni/Au (5µm, 10µm, 15µm and 25µm)
for ACF, NCP and ICA adhesive Flip Chip attach

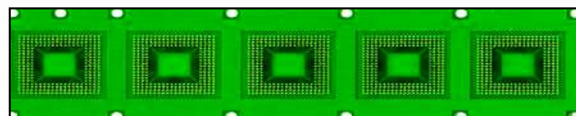
Solder bumps
-SnPb 63/37, SnAg4Cu0,5
-other alloys on request (e.g. PbSn 90/10, AuSn 80/20)

•Electrical Measurements

-Daisy Chain Structures
-Four Point Kelvin Structures

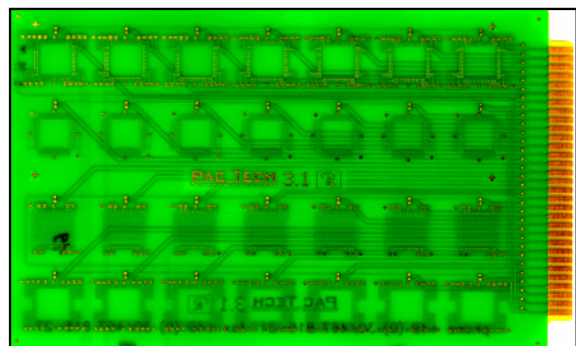
•Printed Circuit Board (Layout PacTech 3.1)

Flip Chip Testkit Pac 2.0
-1 Testwafer Pac 2,0
-4 Printed circuit boards (layout PacTech 3.1)



Pac Tech Testboard BGA 4.0

Flip Chip in Package (FCIP)



Pac Tech Testboard 3.0

Flip Chip on Board (FCOB)

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